

Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

	11102 0 0 1/1 110 0 2 8 8	<u> </u>				
PCN #: SR-040 3		MEANS OF DISTINGUISHING CHANGED DEVICES:				
Product Affected:	PB36 (400 mil SOJ) package type (see attachment for affected part #s)	☐ Product Mark ■ Back Mark Lot number will have "K" prefix. ☐ Date Code				
	5/2004	□ Other				
Contact: Geoffrey (
	QA / Reliability Manager	Attachment:: Yes No				
Phone #: (408) 492-		0 1 0 4 1 4				
Fax #: (408) 727- E-mail: Geoffrey.		Samples: See attachment				
	Cortes@idt.com D PURPOSE OF CHANGE:					
□ Die Technology□ Wafer Fabrication□ Assembly Process□ Equipment	a Process					
 □ Material □ Testing ■ Manufacturing Site □ Data Sheet □ Other □ Other □ To transfer the assembly of PB36 (400 mil SOJ) from Amkor Technology Korea (ATK) to IDT-Manila (Philippines) facility. The other (400 mil SOJ) packages are qualified and are presently being assembled at IDT-Philippines. 						
RELIABILITY/QUALIFICATION SUMMARY: Please see attachment for reliability/qualification data.						
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.						
Customer:	·	☐ Approval for shipments prior to effective date.				
Name/Date:		E-Mail Address:				
Title:		none# /Fax# :				
CUSTOMER COM	MENTS:					
IDT ACKNOWLEI	OGMENT OF RECEIPT:					
RECD. BY:		DATE:				

Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: SR-0403-02

PCN Type: Assembly Facility Change

Data Sheet Change: There is no change in Moisture Sensitive Level (MSL).

Detail of Change: IDT-Manila (Philippines) is a qualified assembly facility for (SOJ) package family. IDT is

transferring an additional package type to this facility.

There is no change in the assembly material set and the package tooling will be transferred from

Amkor Technology Korea (ATK) to IDT-Manila (Philippines) facility.

Description	Assembly Facility Change		
Description	From	То	
PB36 (SOJ) packages	Amkor Technology Korea (ATK)	IDT-Manila (Philippines)	

The affected products are as follow:

IDT71V424L10Y	IDT71V424L15YI	IDT71V424S12YI
IDT71V424L12Y	IDT71V424S10Y	IDT71V424S15Y
IDT71V424L12YI	IDT71V424S10YI	IDT71V424S15YI
IDT71V424L15Y	IDT71V424S12Y	

Note: For T & R (shipping method) "8" is added to the part number and for industrial grade, letter "I" is added to the part number.

Samples are not built ahead of the change and are limited to selective devices. Please contact your local field sales representative for sample availability and additional information.



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: SR-0403-02

Qualification Plan: P03-10-03 **Test Vehicle:** IDT71V424 **Qualification Test Plan and Results:**

Test Description	Test Method	Sample Size /# of Fails	Test Results
*Highly Accelerated Stress Test (HAST) (100 Hrs, @130°C/85%RH,Static Bias)	JESD22-A110-B	45/0	45/0
*Temperature Cycling (-65°C to +150°C, 500 cycle)	JESD22-A104-B	45/0	45/0
*Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	JESD22-A102-C	45/0	45/0
Physical Dimensions	JESD22-B100-B	5/0	5/0
Resistance to Solvents	MIL-STD-883, M 2015	3/0	3/0
Solderability	JESD22-B102-C J-STD-002	3/0	3/0
Bake & Ball Shear Test	JESD22-B116	5/0	5/0
Bond Pull Test	MIL-STD-883, M 2011	5/0	5/0
X-ray Examination	MIL-STD-883, M 2015	45/0	45/0
Adhesion of Lead Finish	MIL-STD-883, M 2025	3/0	3/0
Lead Integrity Test	JESD22-B105C	3/0	3/0
External Visual Inspection	JESD22-B101	25/0	25/0
Internal Visual Inspection	MIL-STD-883, M 2010	5/0	5/0
Moisture Sensitive Level	J-STD-020B	90/0	90/0

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113C.